

ABSTRACT

The present invention has for its object to provide an apparatus and a method for feeding electronic components to a mounting head with high productivity.

5 In order to accomplish the object of the present invention, an electronic component (2) taken out from a component storage section (3) by a transfer head (4) is held by means of a suction operation and transferred and inspected as to whether it is good or defective by a
10 good/defective component inspecting device (6). Thereafter the electronic component is delivered to an alignment suction nozzle (9) on a component alignment section (13). The sequence of the above-operations is repeated, whereby the electronic components (2) inspected and then aligned in
15 the order of mounting can be supplied to a mounting head (10).

 According to the present invention, a mount time for the electronic components in a mount process is greatly shortened, so that productivity is expected to be improved.
20 The electronic components can be inspected before aligned in the order of mounting, which further enhances mount efficiency.